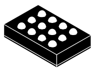
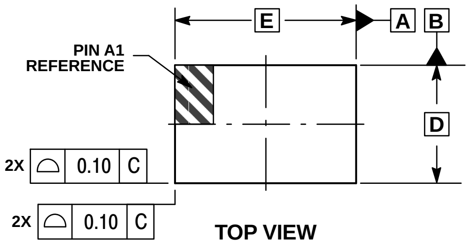


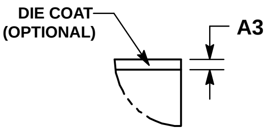
SCALE 4:1

WLCSP12, 1.3x2.0
CASE 567JM
ISSUE A

DATE 02 JUL 2014



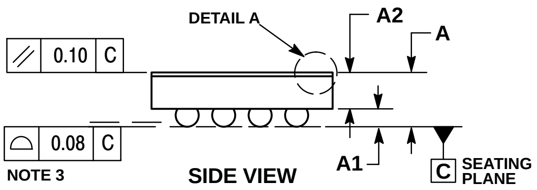
TOP VIEW



DETAIL A

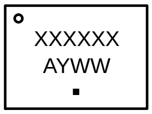
NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.60
A1	0.17	0.23
A2	0.36 REF	
A3	0.04 REF	
b	0.24	0.30
D	1.26	1.31
E	2.01	2.04
e	0.40 BSC	



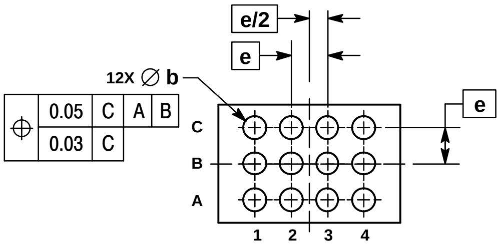
SIDE VIEW

GENERIC MARKING DIAGRAM*



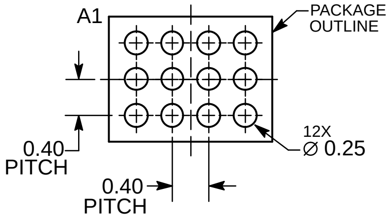
A = Assembly Location
Y = Year
WW = Work Week
▪ = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.



BOTTOM VIEW

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	WLCSP12, 1.3X2.0	PAGE 1 OF 2

ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION. REQ. BY J. SAMUDIO.	09 DEC 2013
A	CHANGED DIMENSIONS A3, D AND E. REQ. BY R. AVILA.	02 JUL 2014

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